

650V Power MOSFET
● General Description

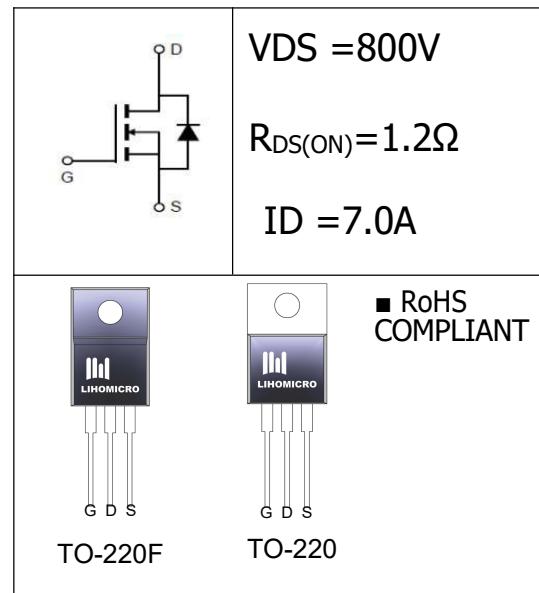
The Power MOSFET LH7N80 with a low resistance package to provide extremely low RDS(ON).This device is ideal for switch power and LED power.

● Features

- LOW thermal resistance
- FSAT switching
- HIGH input resistance
- RoHS compliant

● Application

- Electronic ballast
- Electronic transformer
- Switch mode power supply


● Ordering Information:

Part number	LH7N80	LH7N80
Package	TO-220F	TO-220
Basic ordering unit (pcs)	1000	1000
Normal Package Material Ordering Code	LH7N80F-T0220F-TU	LH7N80T-T0220-TU
Halogen Free Ordering Code	LH7N80F-T0220F-TU-HF	LH7N80T-T0220-TU-HF

● Absolute Maximum Ratings (T_C = 25°C)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	800	V
Gate-Source Voltage	V _{GS}	±30	V
Continuous Drain Current T _C = 25°C	I _D	7.0	A
Continuous Drain Current T _C = 100°C	I _D	4.2	A
Pulsed drain current	I _{DM} ¹	28	A
Single Pulse Avalanche Energy	EAS ²	340	mJ
Total Power Dissipation(TC=25°C)	P _{tot}	TO-220:167	W
		TO-220F:48	
Operating Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55-150	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	800			V
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_j$	$I_D=250\mu A$, Referenced to $25^\circ C$		0.65		V/ $^\circ C$
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.0		4.0	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=800V, V_{GS}=0V, T_j=25^\circ C$			1	uA
		$V_{DS}=640V, V_{GS}=0V, T_j=125^\circ C$			10	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 30V$			± 100	uA
Static Drain-source On	$R_{DS(ON)}$	$V_{GS}=10V, I_D=3.5A$	3	1.2	1.7	Ω
Transconductance	g_{fs}	$V_{DS}=15V, I_D=3.5A$	3	7.0		S

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=25V$ $F=1.0MHz$		1290		pF
Output capacitance	C_{oss}			120		
Reverse transfer capacitance	C_{rss}			21		
Turn-Off Delay Time	$T_{d(off)}$	$V_{DD}=400V, I_D=7.0A$ $R_G=25\Omega$	3	80		ns
Total Gate Charge	Q_g	$I_D=7.0A, V_{DS}=400V$ $V_{GS}=10V$		24		nC
Gate-to-Source Charge	Q_{gs}			6.1		
Gate-to-Drain Charge	Q_{gd}			7.7		
Diode Forward Voltage	V_{SD}	$T_j=25^\circ C, I_S=7.0A$ $V_{GS}=0V$	3		1.4	V
Body Diode Reverse Recovery Time	T_{rr}	$T_j=25^\circ C, I_f=7.0A$ $di/dt=100A/\mu s$		320		ns
Body Diode Reverse Recovery Charge	Q_{rr}			2.4		nC
Continuous Source Current (body diode)	I_S				7.0	A

•Thermal resistance

Parameter	Symbol	Max.		Unit
		TO-220FP(L)	TO-220	
Thermal resistance, junction - case	R _{thJC}	2.60	0.75	°C/W
Thermal resistance, junction - ambient	R _{thJA}	62.5	62.5	°C/W

Notes:

1. Repetitive rating: Pulse width limited by maximum junction temperature
2. Starting T_J=25°C, V_{DD} =50V, L=14mH, R_G =25Ω, I_{AS}=7.0A
3. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%

Typical Characteristics

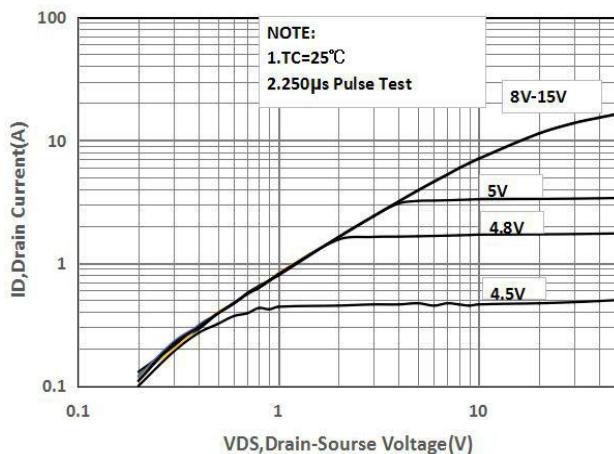


Fig1 Typical Output Characteristics, $T_c=25^\circ\text{C}$

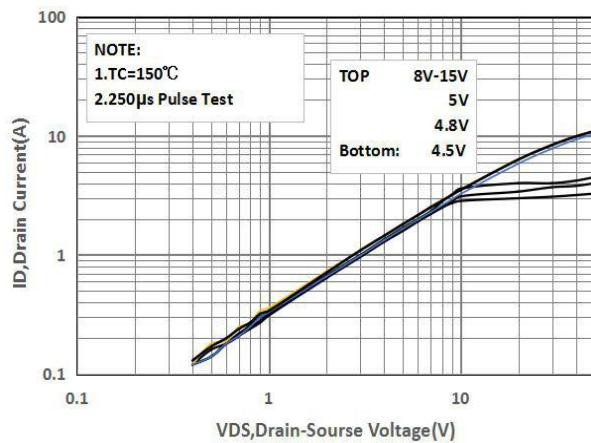


Fig2 Typical Output Characteristics, $T_c=150^\circ\text{C}$

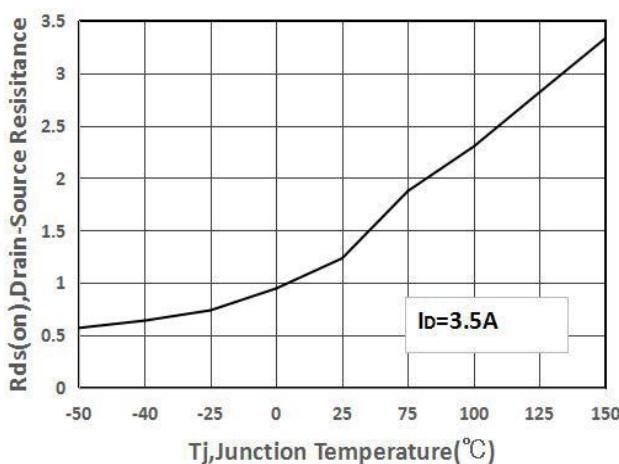


Fig3 Drain-Source On-Resistance Vs.Temperature

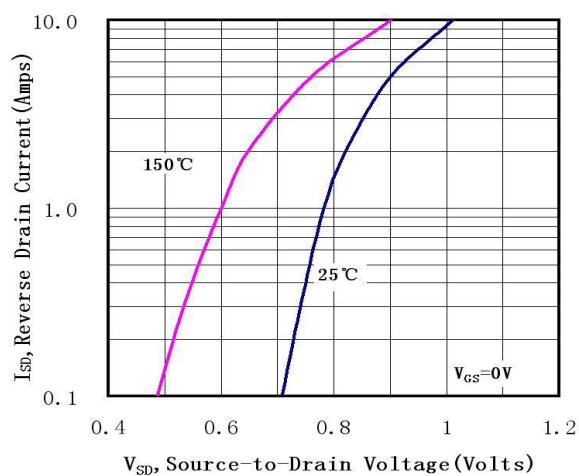


Fig4 Typical Source-Drain Diode Forward Voltage

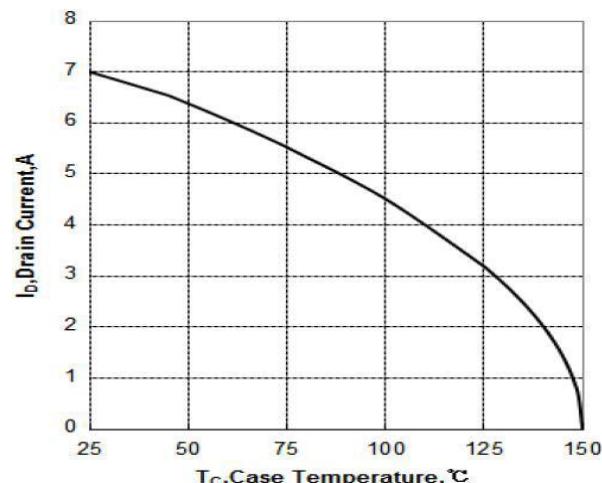


Fig5 Maximum Drain Current Vs.Case Temperature

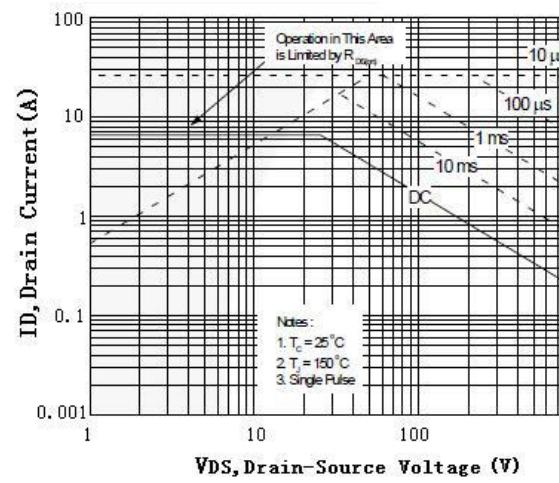
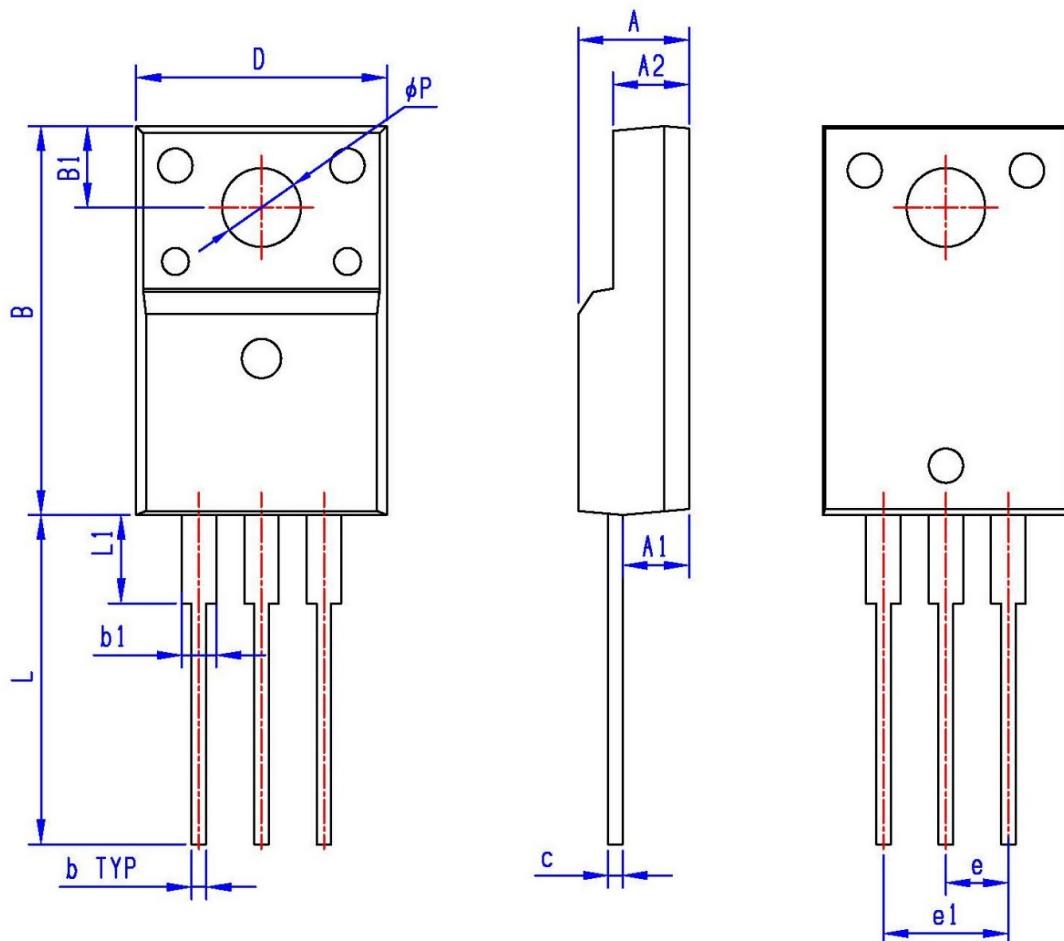


Fig6 Maximum Safe Operating Area

- **Dimensions (TO-220F)**

UNIT: mm

SYMBOL	min	max	SYMBOL	min	max
A	4.40	4.90	B1	2.90	3.70
A1	2.40	3.00	e	2.40	2.70
A2	2.30	3.00	e1	4.95	5.25
b	0.60	0.90	L	12.40	14.20
b1	1.10	1.70	L1	2.40	3.40
c	0.40	0.70	ØP	2.90	3.50
D	9.80	10.60			
B	15.40	16.40			



• Dimensions (TO-220)

UNIT: mm

SYMBOL	min	max	SYMBOL	min	max
A	4.25	4.85	B1	2.60	3.00
A1	2.30	3.00	e	2.40	2.70
A2	1.20	1.40	e1	4.95	5.25
b	0.60	0.90	L	12.60	14.40
b1	1.10	1.70	L1	2.40	4.00
c	0.40	0.70	øP	3.50	3.90
D	9.80	10.60			
B	15.20	16.20			

